EPO-TEK® MED-354-T

Technical Data Sheet
For Reference Only
Biocompatible/Thixotropic Epoxy
ISO 10993-5 Tested/Compliant

Date:	February 2018	
Rev:	II	
No. of Components:	Two	
Mix Ratio by Weight:	10 : 1	
Specific Gravity:	Part A: 1.12	Part B: 1.15
Pot Life:	3 Days	
Shelf Life- Bulk:	Six months at room temperature	

Biocompatible Certified Cure: 150°C / 45 Minutes

Alternative cures are possible, but no certification or testing has been done to support them. Contact techserv@epotek.com with questions.

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Component suppliers assure Epoxy that all components are supplied in compliance with ISO 22442. Sales of EPO-TEK® MED-354-T shall accordingly require Epoxy's Standard Specification document to be signed as a technical agreement thereunder.

Product Description: EPO-TEK® MED-354-T is a biocompatible, high Tg, thixotropic version of EPO-TEK® MED-354 epoxy. It is electrically and thermally insulating and formulated for medical applications with fiber optics, optoelectronic assemblies, as well as semiconductor packaging.

Typical Properties: Cure condition: 150°C / 45 Minutes Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Tan	Part B: Amber	
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 20 rpm:	11,000-20,000	cPs	
Thixotropic Index:	3.0		
* Glass Transition Temp:	≥ 95	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	54	x 10^{-6} in/in°C	
Above Tg:	161	x 10^{-6} in/in°C	
Shore D Hardness:	80		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 15	Kg	5,334 psi
Degradation Temp:	421	°C	
Weight Loss:			
@ 200°C:	0.24	%	
@ 250°C:	0.52	%	
@ 300°C:	1.10	%	
Suggested Operating Temperature:	< 350	°C (Intermittent)	
Storage Modulus:	442,736	psi	
* Particle Size:	≤ 20	microns	

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